ZZ1  These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ2  These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ3  These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
ZZ4  After verifying lens of A1 is clean and undistorted, snap cover H8 over sensor A1 during final hardware assembly.
<table>
<thead>
<tr>
<th>COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.</th>
<th>ASSEMBLY VARIANT: 001</th>
</tr>
</thead>
<tbody>
<tr>
<td>PCB VIEWED FROM BOTTOM SIDE</td>
<td>BOARD #: TIDA-01476</td>
</tr>
<tr>
<td>TID #: TIDA-01476</td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 7/19/2017 1:52:08 PM</td>
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